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Power Resistor for Mounting onto a Heatsink Thick Film Technology



FEATURES

• LPS high power: 1100 W



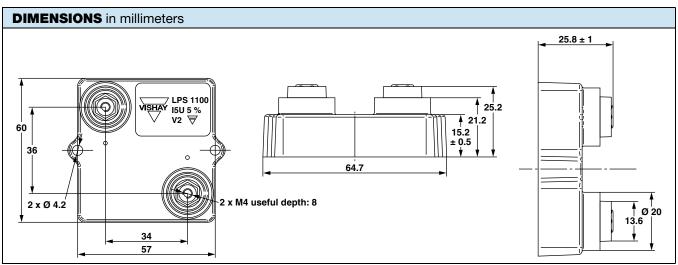
• Wide resistance range: 1 Ω to 1.3 k Ω E24 series

- · Non inductive
- · Easy mounting
- · Low thermal radiation of the case
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESIGN SUPPORT TOOLS







- Notes

 Tolerances unless stated: ± 0.2 mm
 Power dissipation is 1100 W by using a water cooled heatsink at T_{water} = 15 °C of R_{th} = 0.059 °C/W (25 °C to the nearest point of the resistor onto heatsink) and R_{th} contact estimated at 0.07 °C/W

STANDARD ELECTRICAL SPECIFICATIONS				
MODEL	RESISTANCE RANGE Ω	RATED POWER P _{25 °C} W	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C
LPS 1100	1 to 1.3K	1100	1, 2, 5, 10	150

MECHANICAL SPECIFICATIONS			
Mechanical Protection	Insulated case and resin for potting UL 94 V-0		
Resistive Element	Thick film		
End Connections	Screws M4		
Tightening Torque Connections	2 Nm		
Tightening Torque Heatsink	2 Nm		
Maximum Torque	2.5 Nm		
Weight	79 g ± 10 %		

ENVIRONMENTAL SPECIFICATIONS			
Temperature Range	-55 °C to +200 °C		
Climatic Category	55 / 200 / 56		

TECHNICAL SPECIFICATIONS			
Power Rating and Thermal Resistance	1100 W at +25 °C On heatsink R _{th(i-c)} : 0.039 °C/W		
Temperature Coefficient (- 55 °C to + 200 °C), IEC 60115-1	$R \le 1 \ \Omega$: $\pm 500 \ \text{ppm/°C}$ 1 $\Omega < R \le 10 \ \Omega$: $\pm 300 \ \text{ppm/°C}$ 10 $\Omega < R$: $\pm 150 \ \text{ppm/°C}$		
Dielectric Strength IEC 60115-1, 1 min, 10 mA max.	7 kV _{RMS} or 12 kV _{RMS}		
Lightning test 1.2/50 μs IEC 61000-4-5	Until 12 kV		
Insulation	$\geq 10^4 \ \text{M}\Omega$		
Inductance	≤ 0.1 µH		
Partial Discharge (for LPS 1100 D only)	\leq 100 pC/7 kV \leq 10 pC/5 kV Other cases: Consult us		

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PERFORMANCE				
TESTS	CONDITIONS	REQUIREMENTS		
Momentary Overload	IEC 60115-1: 2 x P_r / 10 s for heatsink with $R_{th(h-a)} \geq 0.26$ °C/W (maximum power: 700 W) 1.6 x P_r / 1 s for heatsink with 0.26 °C/W > $R_{th(h-a)} \geq 0.059$ °C/W (maximum power: 1800 W)	± (0.25 % + 0.05 Ω)		
D. H.T.	AEC-Q200 conditions: IEC 60115-1/IEC 60068-2-14, Test Na 50 cycles (-55 °C to +200 °C)	\pm (0.5 $\%$ + 0.05 $\Omega)$ for all the ohmic values		
Rapid Temperature Change	1000 cycles (-55 °C to +200 °C)	\pm (5 % + 0.05 Ω) for R < 38 Ω \pm (0.5 % + 0.05 Ω) for R ≥ 38 Ω		
Load Life AEC-Q200 conditions: IEC 60115-1 2000 h (90/30) P _r		\pm (5 % + 0.05 Ω) for R < 38 Ω \pm (0.5 % + 0.05 Ω) for R ≥ 38 Ω		
Humidity (Steady State)	AEC-Q200 conditions: IEC 60115-1, 1000 h RH 85 % / 85 °C	$\pm (0.5 \% + 0.05 \Omega)$		
Mechanical Shock AEC-Q200 conditions: MIL-STD-202 method 213 condition D (100 g's / 6 ms 3.75 m/s)		± (1 % + 0.05 Ω)		
Vibration	Vibration AEC-Q200 conditions: MIL-STD-202 method 204 condition D (5 g, 20 min 10/2000 Hz)			
Climatic Sequence	AEC-Q200 conditions: IEC 60115-1 (55 / 200 / 56)	± (1 % + 0.05 Ω)		

RECOMMENDATIONS FOR MOUNTING ONTO A HEATSINK

- · Surfaces in contact must be carefully cleaned
- The heatsink must have an acceptable flatness: From 0.05 mm to 0.1 mm/100 mm
- Roughness of the heatsink must be around 6.3 µm. In order to improve thermal conductivity, surfaces in contact (ceramic, heatsink) should be coated with a silicone grease (type Bluesil Past 340 from Blue Star Silicones). Thermal film (type Q-pad II from Berquist) is also possible, easier and faster to install than grease but with a lower efficiency for the power dissipation
- The fastening of the resistor to the heatsink is under pressure control of two screws tightened at 2 Nm for full power availability

Tightening Torque on Heatsink	LPS 1100
Tightening Torque on Heatsink	2 Nm

- The following accessories are supplied with each product:
 - 2 screws CHC M4 x 25 class 8.8 and 2 M4 contact lock washers for heatsink mounting
 - 2 screws TH M4 x 6/6 and 2 M4 contact lock washers for connections

CHOICE OF THE HEATSINK AND THE THERMAL INTERFACE

The user must choose the heatsink according to the working conditions of the component (power, room temperature). Maximum working temperature must not exceed 200 °C. The dissipated power is simply calculated by the following ratio:

$$P = \frac{\Delta T}{[R_{th (j-c)}] + [R_{th (c-h)}] + [R_{th (h-a)}]}$$

P: Expressed in W

ΔT: Difference between maximum working temperature and room temperature or fluid cooling temperature

R_{th (j - c)}: Thermal resistance value measured between resistive layer and outer side of the resistor. It is the thermal resistance of the component: 0.039 °C/W

R_{th (c - h)}: Thermal resistance value measured between outer side of the resistor and upper side of the heatsink. This is the thermal resistance of the interface (grease, thermal pad), and the quality of the fastening device

R_{th (h - a)}: Thermal resistance of the heatsink

Example:

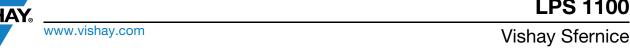
R_{th (c - h)} + R_{th (h - a)} for LPS 1100 power dissipation 850 W at + 18 °C fluid temperature

$$\Delta T \le 200 \, ^{\circ}\text{C} - 18 \, ^{\circ}\text{C} = 182 \, ^{\circ}\text{C}$$

$$R_{\text{th (j-c)}} + R_{\text{TH (c-h)}} + R_{\text{TH (h-a)}} = \frac{\Delta T}{P} = \frac{182}{850} = 0.214 \, ^{\circ}\text{C/W}$$

$$R_{th (i - c)} = 0.039 \, {}^{\circ}C/W$$

$$R_{th (c-h)} + R_{th (h-a)} = 0.214 \text{ °C/W} - 0.039 \text{ °C/W} = 0.175 \text{ °C/W}$$



	CONFIG. 1: WATER COOLING HEATSINK CP15 AND THERMAL GREASE BLUESIL PAST 340	CONFIG. 2: AIR COOLING HEATSINK P207/250 AND THERMAL GREASE BLUESIL PAST 340	CONFIG. 3: WATER COOLING HEATSINK CP15 AND THERMAL PAD Q-PAD II	CONFIG. 4: AIR COOLING HEATSINK P207/250 AND THERMAL PAD Q-PAD II
Power Dissipation (W)	1100	350	650	285
T° Resistive Element (°C)	200	200	200	200
R _{th(j-c)} max. (°C/W)	0.039	0.039	0.039	0.039
R _{th(c-h)} typ. (°C/W)	0.070	0.201	0.187	0.315
R _{th(h-a)} max. (°C/W)	0.059	0.260	0.059	0.260
Fluid T° (°C)	15 (water)	25 (air)	15 (water)	25 (air)

Note

- Configuration 1: Water cooling heatsink (CP15 from Lytron (304 mm x 95.3 mm x 8 mm) with water flow rate 4LPM and thermal grease Bluesil Past 340 from BlueStar Silicones
 - Configuration 2: Air cooling heatsink P207/250 from Semikron (250 mm x 200 mm x 72 mm) and thermal grease Bluesil Past 340 from BlueStar Silicones
 - Configuration 3: Water cooling heatsink (CP15 from Lytron (304 mm x 95.3 mm x 8 mm) with water flow rate 4LPM and thermal pad Q-pad II from Berquist
 - Configuration 4: Air cooling heatsink P207/250 from Semikron (250 mm x 200 mm x 72 mm) and thermal pad Q-pad II from Berquist

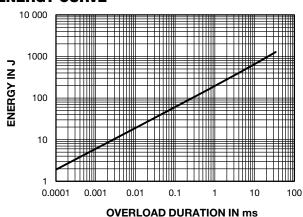
OVERLOAD

In any case the applied voltage must be lower than $U_{\rm I} = 6600 \text{ V}.$

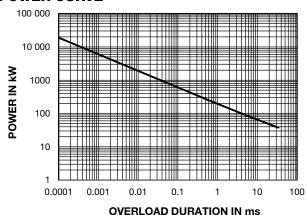
Short time overload: 2 x Pr/10 s for heatsink with $R_{th(h\text{-}a)} \geq$ 0.26 °C/W (maximum power: 700 W) and 1.6 x Pr/1 s for heatsink with 0.26 °C/W > $R_{th(h\text{-}a)} \geq$ 0.059 °C/W (maximum power: 1800 W).

Accidental overload: The values indicated on the following graph are applicable to resistors in air or mounted onto a heatsink.

ENERGY CURVE



POWER CURVE

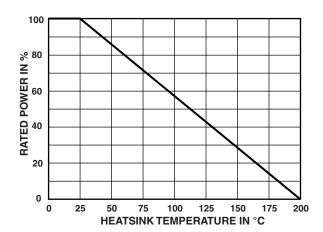


MARKING

Series, style, ohmic value (in Ω), tolerance (in %), manufacturing date, Vishay Sfernice trademark.

POWER RATING

The temperature of the case should be maintained within the limit specified in the following figure. To optimize the thermal conduction, contacting surfaces should be coated with silicone grease or thermal film, and heatsink mounting screws tightened to 2 Nm.



PACKAGING

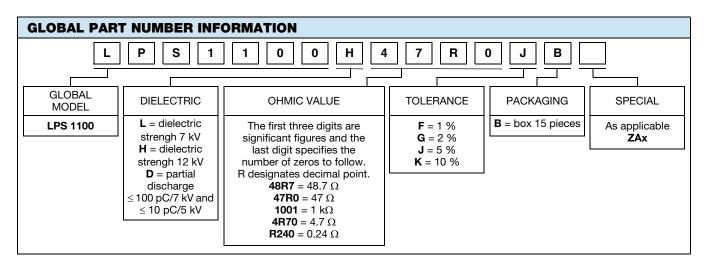
Box of 15 units



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ORDERING II	NFORMATION	1				
LPS	1100	1 k Ω	± 1 %	xxx	BO15	е
MODEL	STYLE	RESISTANCE VALUE	TOLERANCE	CUSTOM DESIGN	PACKAGING	LEAD (Pb)-FREE
			± 1 % ± 2 % ± 5 % ± 10 %	Optional on request: special TCR, shape, etc.		





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